

HSF

NOTES:

Current Rating: 3.0AMP
 Contact Resistance: 35mΩ Max
 Withstand Voltage: 500V AC/DC
 Insulation Resistance: 500MΩ Min
 Operation Temperature: -40°C to +105°C

Contact Material: Phosphor Bronze
 Contact Plating: Au and Sn over Ni
 Shell Material: Zinc Alloy
 Shell Plating: Ni 100u"
 Fixing Material: Phosphor Bronze
 Fixing Plating: Sn over Ni
 Housing Material: PBT+30%G.F(UL94V-0)
 Cover Material: PBT+30%G.F(UL94V-0)

Ordering Information

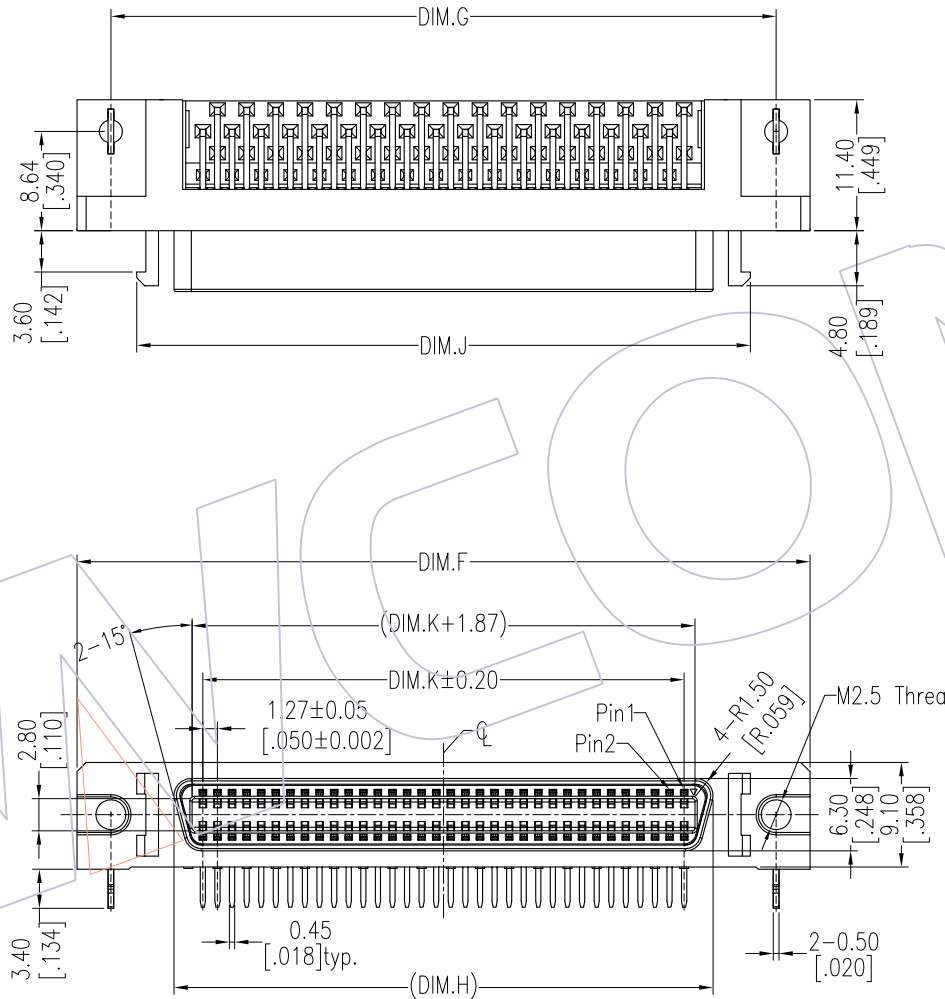
6321-0 XX R D SX M W A 01

No. of Pins
 14P 36P
 20P 50P
 26P 68P

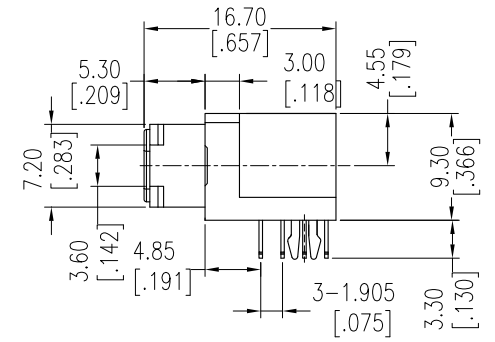
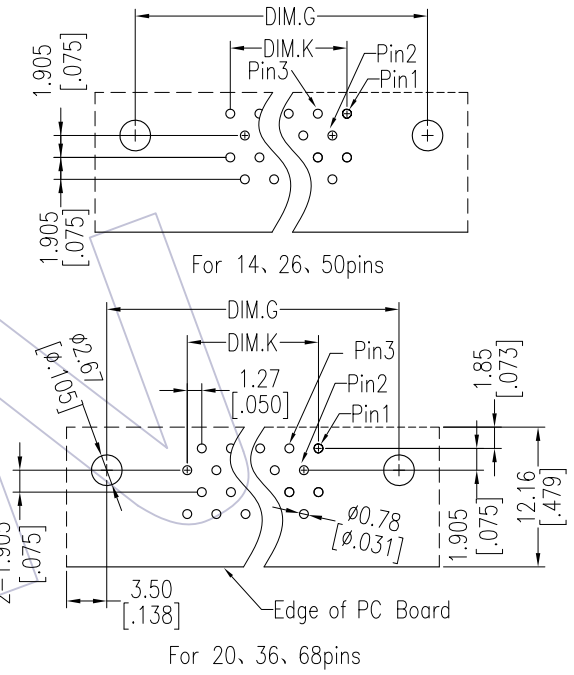
Contact Plating
 S1=3u"Gold/Tin
 S3=10u"Gold/Tin
 S4=15u"Gold/Tin
 S5=30u"Gold/Tin

A=Tray

53.43	41.91	46.83	57.93	63.83	68
42.00	30.48	35.40	46.50	52.40	50
33.11	21.59	26.51	37.61	43.51	36
26.76	15.24	20.16	31.26	37.16	26
22.95	11.43	16.35	27.45	33.35	20
19.14	7.62	12.54	23.64	29.54	14
DIM.J	DIM.K	DIM.H	DIM.G	DIM.F	PIN数



Recommended P.C.B Layout(Top Side)
 (PCB BOARD TOLERANCE±0.05)



				OPERATION		DRAW		DATE		SCALE		FIT		PART NO.	
				x.X ±0.40		JYHuang		2013/08/28		UNIT		mm		6321-0XXRDSXMWA01	
A1		2013/08/28		x.XX ±0.25		CHECK		DATE		SIZE		A4		TITLE:	
A0		2013/07/03		x.XXX ±0.15		APPROVE		DATE		SHEET		1/2		1.27PITCH CEN TYPE SCSI FEMALE DIP (鱼叉纵向)	
REV		DATE		MODIFICATION DESCRIPTION		CHANGE		DATE		PROJ.		Customer NO.			
				Angle ± 3°											
				DIM TOL											